

Opto-semiconductor Modules

Related products and circuits that enable semiconductor elements to operate at peak performance. A broad range of customization is available.



Opto-semiconductor Modules

Related products and circuits that enable opto-semiconductor devices to operate at peak performance

Here at Hamamatsu Photonics, we use the unique opto-semiconductor technology that we have accumulated over the years to develop and manufacture photodiodes, APDs, MPPCs, image sensors, LEDs, and other opto-semiconductors. To make these opto-semiconductors easier to use and more widely used, we have developed opto-semiconductor modules that combine Hamamatsu opto-semiconductor, optic, circuit, mounting, software, and MEMS technologies.

We can also provide customized products. Feel free to contact us with your request.

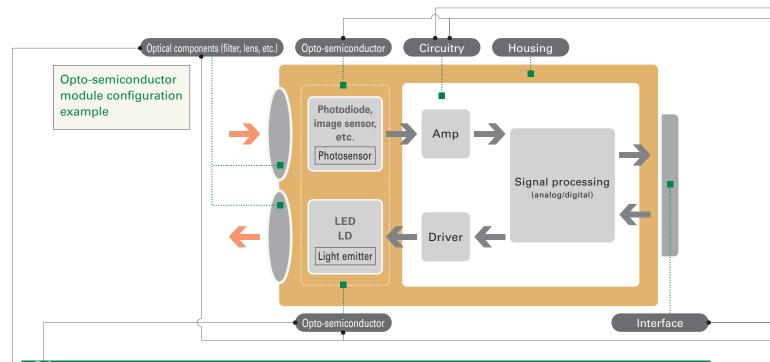


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Technologies that create opto-semiconductor modules

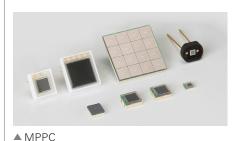


01 Opto-semiconductor technology

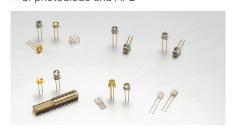
- The detector, which is the heart of the module, uses Hamamatsu opto-semiconductors, which have a long track record for many years in the fields of analysis, measurement, automotive, and consumer products.
- Not only can you select photosensors and light sources from the wide lineup of opto-semiconductors that Hamamatsu has developed, you can also have them custom designed to achieve the features that you want.



▲ Si photodiode and APD







▲ Image sensor

▲ LED

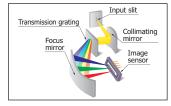
02 Optical technology

- Optimal optical design leads to high-performance modules.
- Use of simulations

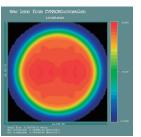
We perform optics simulations in-house to create optical designs quickly and flexibly.

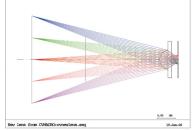


▲ Inside of a mini-spectrometer



▲ Optical system layout example of a mini-spectrometer

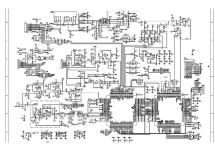




▲ Optical simulation example

03 Circuit technology

- Optimized for optical devices and applications
- Supports high sensitivity, low noise, high speed, and multiple channels



▲ Circuit example



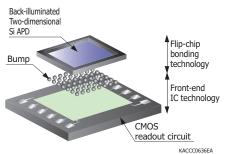
▲ Circuit mounting example

U4 Mounting technology

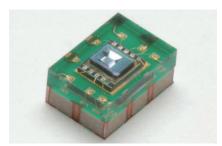
- Our mounting technology combines compactness, high functionality, and low cost.

 Flip-chip bonding technology: A flip chip is directly bonded to a board through the use of solder bumps.

 Front-end IC technology: A custom first-stage analog signal processing circuit and a photosensitive area are bonded together.
- COB (chip on board): A chip is directly mounted onto a board, and this results in a smaller mounting area, a thinner module, and a lower cost.
- A photosensor and optical component, etc. are bonded to a board, and this results in a smaller size and a lower cost.



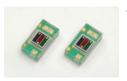
▲ Example of our mounting technology applied



▲ Hybrid device (using front-end IC technology)

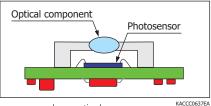


 Chip-size packages (Flip-chip bonding technology is used.)



■ COB





▲ Example in which a photosensor and an optical component are combined (optics module)

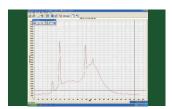


▲ Dual-sided mounting

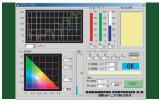


05 Software technology

- The sample software makes swift evaluation possible.
- Support for USB, RS-232C, and other types of interfaces is available.



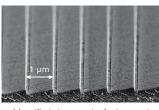
▲ Mini-spectrometer measurement example



▲ Color sensor module measurement example

06 MEMS* technology

- High-precision micromachining
- * Micro-electro-mechanical systems
- Helps make modular components smaller and modules more functional



▲ Magnified photograph of micro-grating



▲ Enlarged photo of slit

Customization example

In addition to offering standard opto-semiconductor modules, Hamamatsu can also provide opto-semiconductor modules that are customized in accordance with the specifications that our customers request.

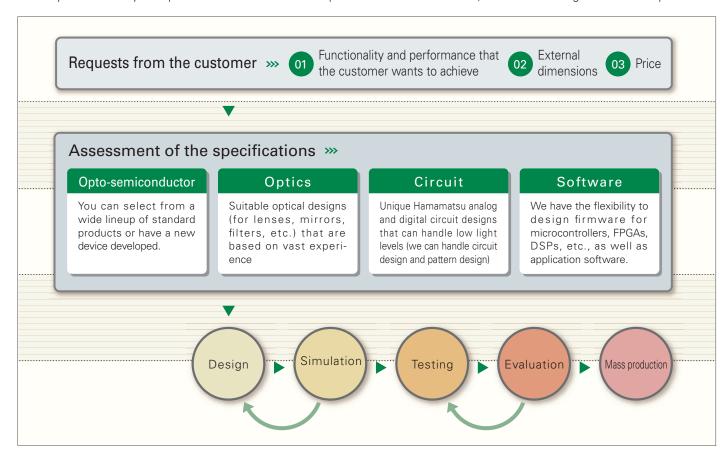
If you have the following requests regarding opto-semiconductor modules, contact your local Hamamatsu office.

- Want to detect light with this wavelength
- Want to detect very low-level light
- Want to detect light at high speeds
- Want to output this type of signal
- Want to miniaturize the detector
- Want to achieve low cost
- Want to use in this type of location



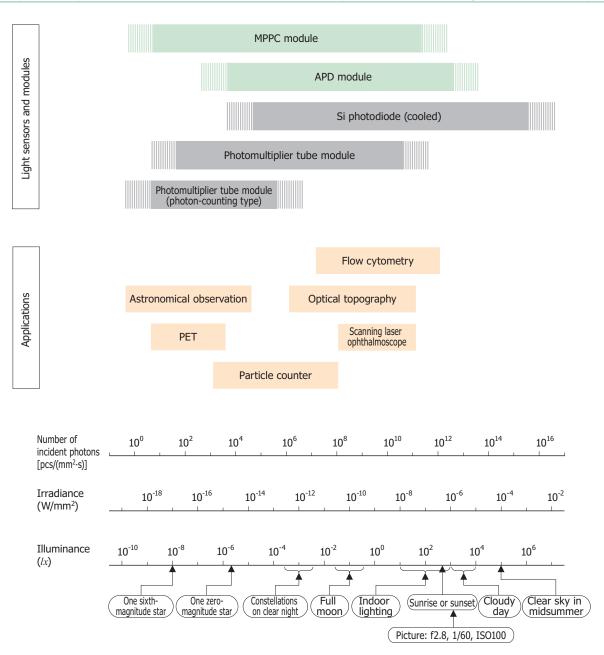
Process for developing a custom product

Not only do we modify the specifications of our standard opto-semiconductor modules, we can also design new custom products.



Low-light-level detection modules

Examples of optical sensors and modules that correspond to different light levels and applications



Note: Reference data

Correlation between the number of incident photons, irradiance, and illuminance is shown for light at λ =555 nm.

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MPPC® modules

MPPC modules are photon counting modules with built-in MPPCs. These modules consist of an MPPC, current-to-voltage converter, high-speed comparator circuit, high-voltage power supply circuit, temperature-compensation circuit, counter circuit, and microcontroller. Excellent photon counting characteristics are achieved by exploiting the full potential of the MPPC.



Analog ou	itput type							(Тур.)				
Type no.	Photo W × D × H (mm)	Built-in MPPC	Effective photosensitive area (mm)	Pixel pitch (µm)	Photoelectric sensitivity (V/W)	Noise equivalent power (fW/Hz ^{1/2})	Temperature control	Supply voltage (V)				
C13365-1350SA		S13360-1350CS	1.3 × 1.3			0.5	Temperature					
C13365-3050SA	36 × 22 × 12.9	S13360-3050CS	3.0 × 3.0	50	1 × 10 ⁹	1.2	compensation (non-cooled)	±5				
C13366-1350GA						TE-cooled type	1.3 × 1.3	30	1 × 10	0.1	TE-cooled	±Ο
C13366-3050GA	98 × 60 × 35	(for precision measurement)	3.0 × 3.0			0.15	(-20 °C)					
C11209-110	29 v 45 v 12	S12571-010C	1.0 × 1.0	10	2.6 × 10 ⁶	3	Temperature compensation (non-cooled)	+5				

Digital out	Digital output type													
Type no.	Photo W × D × H (mm)	Built-in MPPC	Effective photosensitive area (mm)	Pixel pitch (µm)	Photon detection efficiency (%)	Dark count (cps)	Temperature control	Supply voltage (V)						
C13366-1350GD		TE-cooled type	1.3 × 1.3	50	40	2.5 k								
C13366-3050GD	98 × 60 × 35	(for precision measurement)	3.0 × 3.0			12 k	TE-cooled	. E						
C13001-01	98 × 60 × 35	Single p (fiber co	ixel ¢50 µm upling type)		45	7	(-20 °C)	±5						

Starter kit				(тур.)
Type no.	Photo	Temperature control	Supply voltage (V)	Features
C12332-01		Temperature compensation (non-cooled)	±5	 Enables the evaluation of non-cooled MPPCs (sold separately) Includes C11204-01 power supply for MPPC Measurable just by setting MPPC operating voltage from PC

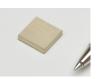
MPPC array modules

Array modules are available in various types. Contact us for detailed information.

- C13368 series: One-dimensional type MPPC array module
- C13369 series: Two-dimensional type MPPC array module Each series has three circuit types (analog, counting, multichannel analyzer).

C11204-01/-02 power supply for MPPC

These are high voltage power supplies that are optimized for driving MPPCs. Since they have a temperature compensation function, MPPCs can be driven stably even in environments subject to temperature changes.



C11204-02

Features

- Wide output voltage range: 50 to 90 V (C11204-01) 40 to 90 V (C11204-02)
- Low ripple noise: 0.1 mVp-p typ.
- Superb temperature stability: ±10 ppm/°C typ.
- High resolution settings (1.8 mV resolution)
- Serial interface
- Surface mount type



APD modules

These modules combine an APD, low-noise amplifier, and bias power supply in a compact form.

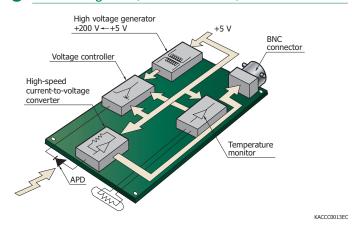


(Typ. unless otherwise noted)

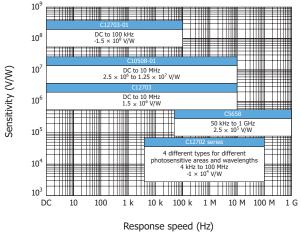
			Photo	Effective	Built-in	Cutoff fr	equency	Photoelectric conversion sensitivity	Minimum detection limit	Temperature	Supply
Ту	rpe	Type no.	W × D × H (mm)	photosensitive area* (mm)	APD	Low speed	ßHigh speed	M=30 λ=800 nm (V/W)	M=30 λ=800 nm (nW rms)	stability of gain 25 ± 10 °C (%)	voltage (V)
	For near infrared light	C12702-03		φ1.0 S12023-10 4 kH;		4 1/11-	100 MHz	-6.8 × 10 ⁴	3	±2.5	+5
\geq		C12702-04		ф3.0	S2384	4 KHZ	80 MHz	-2.3 × 10 ⁴	3.6	±2.5	+5
Stand For short	hort ingths	C12702-11	-80 × 50 × 23	ф1.0	S12053-10	4 kHz	100 MHz	-2.5 × 10 ⁴	5	±2.5	+5
	For s wavele	C12702-12		ф3.0	S5344		40 MHz	-1.9 × 10 ⁴	6.3	12.5	+5
Hi	igh	C12703	Q.95	φ1.5	S3884	DC	10 MHz	1.5 × 10 ⁶	0.63	±2.5	±12
sens	itivity	C12703-01	80 × 50 × 23	ф3.0	S2384	DC	100 kHz	-1.5 × 10 ⁸	0.0063	±2.5	±12
Hi stal	igh pility	C10508-01	60 × 65.6 × 19.6	φ1.0	S12023-10A	DC	10 MHz	1.25 × 10 ⁷	0.063	±5.0 max.	±5
	igh eed	C5658	28 × 50 × 60	ф0.5	S12023-05	50 kHz	1 GHz	2.5 × 10 ⁵	16	±5.0	+12

^{*} Area in which a typical gain can be obtained

Block diagram (C12702 series)



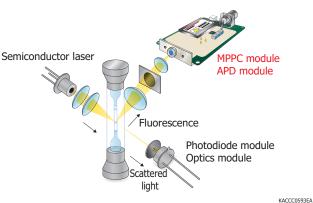
Sensitivity and response speed



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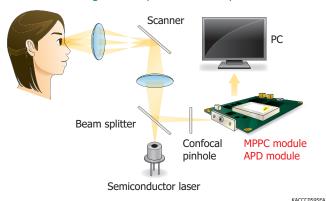
Application examples

[Flow cytometry]



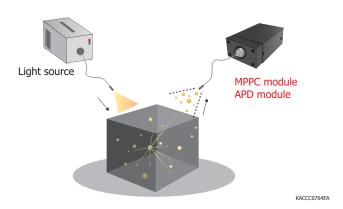
So that the type, number, and nucleic acids (DNA and RNA) of cells can be detected, a liquid that contains cells is made to flow at high speeds and is irradiated with a laser. The resulting faint fluorescence is detected.

[Scanning laser ophthalmoscope (SLO)]



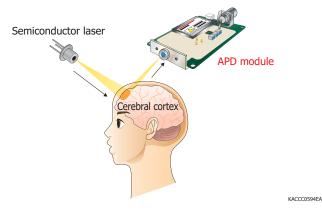
In ophthalmoscopy, for safety reasons, the laser light that is irradiated into the eyeball must have a low intensity. MPPC and APD modules can be used to detect faint reflected light from the eye-ball with superior resolution and contrast.

[Particle counter]



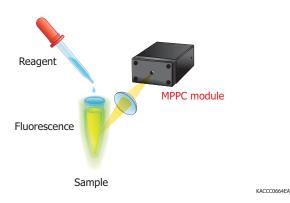
When a laser is made to pass through a chamber that contains a gas or liquid with particles, the quantity and size distributions of the particles in the chamber can be determined through the detection of the light that is scattered by the particles.

[Optical topography]



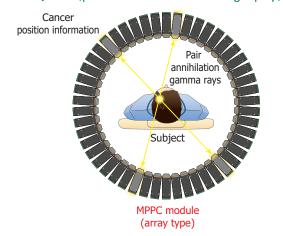
So that changes in the amount of blood flow in the cerebral cortex can be detected, near infrared light is irradiated from above the head, an APD module detects scattered light, and changes in the hemoglobin density of the blood are thereby detected.

[Fluorescence measurement]



The MPPC module can detect minute fluorescence emission of reagents.

[PET (positron emission tomography)]



MPPCs that are arranged 360° around a subject detect pair annihilation gamma rays, and the location of a target, such as cancer, can be determined on the basis of the detected intersections.

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Radiation detector modules

The C12137 series is a radiation detector module containing a scintillator and MPPC (multi-pixel photon counter) designed to detect gamma rays such as ¹³⁷Cs (Cesium-137). The scintillator converts incident gamma rays into a visible light which is detectable by the MPPC even at very low light levels to ensure highly accurate measurement of low energy gamma rays. The signal processing circuit and A/D converter come housed in a compact case with a USB interface.



USB type					
Parameter	C12137	C12137-01	C12137-08	C12137-10	Unit
Dimensions (W × D × H)*1	110 × 55 × 27	$71 \times 55 \times 60.5$	112 × 94 × 53.3	122 × 122 × 53.3	mm
Weight	120	320	1130	1570	g
Detector		MF	PC		-
Scintillator		Csl	(TI)		-
Scintillator size (W × D × H)	13 × 13 × 20	38 × 38 × 25	80 × 80 × 25	φ110 × 25	mm
Counting efficiency min.*2	40	400	20	00	cpm
Energy range	0.03	to 2	0.06	to 2	MeV
Energy resolution*3	8	8.5	9	10	%
Measurement range (dose equivalent rate)*4	0.01 to 100	0.001 to 10	*	5	μSv/h
Measurement error*6	±	20	*	5	%
Sampling time		10 to 60 s,	adjustable		-
Interface		USB 2.0 (F	ull Speed)		-
Compatible OS		Windows 7 SP	1 (32-bit, 64-bit)		-
Power supply		USB bus power (150 n	nA typ., 500 mA max.)		-

RS-232C type										
Parameter	C12137-00D	C12137-01D	C12137-08D	C12137-10D	Unit					
Dimensions (W × D × H)*1	110 × 55 × 27	71 × 55 × 60.5	112 × 94 × 55.6	122 × 122 × 55.6	mm					
Weight	160	360	1170	1610	g					
Detector MPPC										
Scintillator CsI(TI)										
Scintillator size (W × D × H)	13 × 13 × 20	38 × 38 × 25	80 × 80 × 25	φ110 × 25	mm					
Counting efficiency min.*2	40	400	20	00	cpm					
Energy range	0.03	to 2	0.06	to 2	MeV					
Energy resolution*3	8	8.5	9	10	%					
Measurement range (dose equivalent rate)*4	0.01 to 100	0.001 to 10	*	5	μSv/h					
Measurement error*6	±	20	*	5	%					
Sampling time		10 to 60 s,	adjustable		-					
Interface		RS-232C (EIA-232-E)		-					
Bit rate		115	200		bps					
Power supply		+5 V (200 mA ty)	p., 500 mA max.)		-					

^{*1:} Excluding the cable and connector

^{*2:} $^{137}Cs,\,0.01~\mu Sv/h$

^{*3: &}lt;sup>137</sup>Cs, 662 keV

^{*4: &}lt;sup>137</sup>Cs, 662 keV*7. The lower limit depends on the environmental radiation.

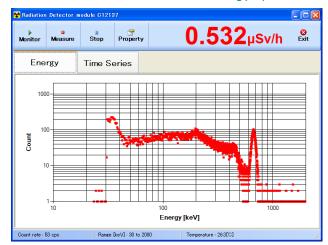
^{*5:} The C12137-08/-08D/-10/-10D do not perform conversion into dose equivalent rate using the G(E) function.

^{*6:} Excludes attenuation (caused by the shield) and counting fluctuations

^{*7:} Measurement range of these products is defined by ¹³⁷Cs. When detecting environmental radiation that mainly consists of low energy radiation, the maximum measurement value will be approx. 1/3 to 1/2 of this figure.

Measurement examples

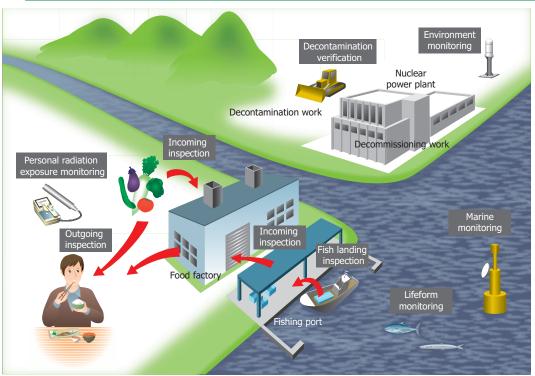
[Cesium-137 radiation source (energy spectrum)]

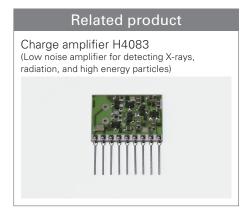


[Environmental radiation (time variation)]



Application examples





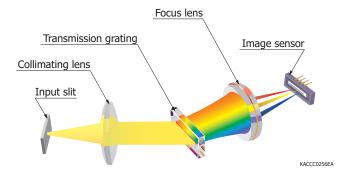
Mini-spectrometers

Mini-spectrometers are compact devices that include a grating and other optical elements and an image sensor. There are modular types that have a built-in driver circuit and head types that do not have a built-in driver circuit.

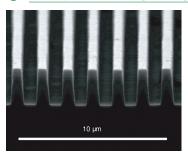


Elemental technologies that go into making mini-spectrometers

Optical system layouts (typical example: TG series)



SEM photo of a grating



The wavelength dispersive elements of the mini-spectrometers (TM and TG series) use a transmission grating (quartz) fabricated by a holographic process. The holographic process is a technique suited for mass production, and a grating can be formed directly onto the matrix, instead of replicating the grating. This grating can separate light into a spectrum precisely and improve measurement throughput. It also reduces stray light levels.

Also, the detector, which is the heart of the mini-spectrometer, uses Hamamatsu image sensors, which have performed exceptionally for many years in the fields of analysis and measurement.

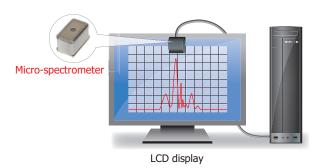
The mini-spectrometer was developed and produced from these elemental technologies.

Image sensors that are built into the mini-spectrometers



Application examples

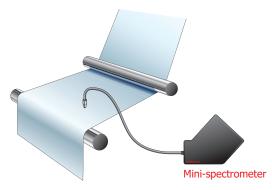
[Display color measurement]



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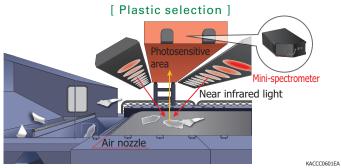
The emission spectrum of an LCD display is monitored through the use of a micro-spectrometer.

[Film thickness measurement]

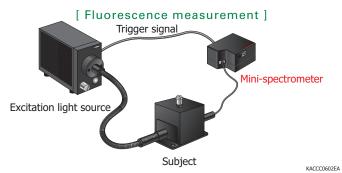


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White light interferometry can be used to determine the thickness of a film on the basis of the number of reflected light's spectral peaks, refractive index, and incident light angle.



Near-infrared light is emitted onto plastics. Different types of plastics absorb different wavelengths, and this fact is used to separate the plastics.



The emission spectra of fluorescent lights, organic EL devices, and other luminescent materials are measured.

(Typ. unless otherwise noted)

	l B						(Typ. unless otherwise noted)			
Type no.	Photo W × D × H (mm)		Туре	Spectral response range (nm)	Wavelength resolution (nm)	Built-in image sensor	Features			
C10082CA	.0,		High sensitivity TM-UV/VIS-CCD		6 max.	Back-thinned CCD	Suitable for spectroscopic measurement (fluorescence			
C10082CAH	95 × 92 × 76		High resolution TM-UV/VIS-CCD	200 to 800	1 typ.	image sensor	measurement, etc.) of low light levels			
C10082MD	94 × 90 × 55	ies	Wide dynamic range TM-UV/VIS-MOS		6 max.	CMOS linear image sensor	Suitable for use in environments with high light levels (light source spectrometry, absorbance measurement, etc.)			
C10083CA	.8 ,	/ series	High sensitivity TM-VIS/NIR-CCD		8 max. (320 to 900 nm)	Back-thinned CCD	Suitable for spectroscopic measurement (fluorescence measurement, etc.) of low			
C10083CAH	95 × 92 × 76	\sqsubseteq	High resolution TM-VIS/NIR-CCD	320 to 1000	1 typ. (320 to 900 nm)	image sensor	light levels			
C10083MD			Wide dynamic range TM-VIS/NIR-MOS	320 10 1000	8 max.	CMOS linear image sensor	Suitable for use in environments with high light levels (light source spectrometry, absorbance measurement, etc.)			
C11697MB	94 × 90 × 55		Triggering TM-VIS/NIR-MOS-II		o max.	High sensitivity CMOS linear image sensor	Triggering Suitable for spectroscopic measurement using pulsed light			
C9404CA	40 -		High sensitivity TG-UV-CCD	200 to 400	3 max.	Back-thinned CCD	Suitable for spectroscopic measurement (fluorescence			
C9404CAH	125.7 × 115.7 × 75		High resolution TG-UV-CCD	200 to 400	1 typ.	image sensor	measurement, etc.) of low light levels			
C11713CA	120 × 70 × 60	es	High resolution TG-RAMAN-I	500 to 600	0.3 typ.	Back-thinned CCD image sensor	Suitable for Raman spectrometry			
C11482GA	38.5 × 106 × 86	G series	No cooling TG2-NIR	900 to 1700	7 max.					
C9913GC		Ĭ	Low noise (cooled type) TG-cooled-NIR-I	000 10 1700	7 max.	InGaAs linear	For near infrared range			
C9914GB	.,00		Low noise (cooled type) TG-cooled-NIR-II	1100 to 2200	8 max.	image sensor	A low-noise, cooled type is available.			
C11118GA	142 × 218 × 80		Low noise (cooled type) TG2-cooled-NIR-III	900 to 2550	20 max.					
C13053MA			Compact, thin TF-SWNIR	500 to 1100	3.5 max.					
C13054MA		es	Compact, thin TF-RAMAN	790 to 920	0.4 typ.	High-sensitivity CMOS linear				
C14214MA	2	F series	Compact, thin TF-RAMAN	790 to 1050	0.6 max.	image sensor	Thin typeTriggering			
C13555MA	80 × 60 × 12*	Ë	Compact, thin TF-VIS	340 to 830	3 max.					
C14486GA			Compact, thin TF-NIR	950 to 1700	7 max.	InGaAs linear image sensor				
C11007MA	4.		Spectrometer module RC-VIS-MOS	340 to 780	9 max.	CMOS linear image sensor	• Compact			
C11008MA	55 × 48 × 100	eries	Spectrometer module RC-SWNIR-MOS	640 to 1050	8 max.	High infrared sensitivity CMOS linear image sensor	Inexpensive			
C11009MA	28 × 28 × 28	RC s	Spectrometer head RC-VIS-MOS	340 to 780	9 max.	CMOS linear image sensor	For incorporating into devices			
C11010MA	35 × 20 × 28		Spectrometer head RC-SWNIR-MOS	640 to 1050	8 max.	High infrared sensitivity CMOS linear image sensor	- 1 of incorporating into devices			
C11708MA	27.6 × 13 × 16.8	MS series	Spectrometer head MS-SWNIR-MOS	640 to 1050	20 max.	CMOS linear image sensor	For near infrared range			
C12666MA		Micro-spectrometer	Spectrometer head	340 to 780	15 may	CMOS linear image sensor	Wide dynamic range			
C12880MA	20.1 × 12.5 × 10.1	Micro-spec	Spectrometer head	340 to 850	15 max.	High-sensitivity CMOS linear image sensor	High sensitivitySimultaneous integration			
* 04 404 414 4	00 00 10									

^{*} C14214MA: $100 \times 60 \times 12$

Spectroscopic module

This is a compact, lightweight Raman spectroscopy analysis module. A compact spectrometer, excitation light source, wavelength filter, and other optical elements are integrated into a single unit. The module can be used for onsite screening tests and other applications that use Raman spectroscopy. In addition, using the surface-enhanced Raman spectroscopy (SERS) substrate makes high-sensitivity Raman spectroscopic analysis possible. The C13560 is a palm-sized lightweight type.

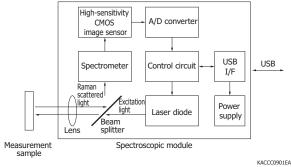


(Typ. unless otherwise noted)

Type no.	Photo W × D × H (mm)	Excitation wavelength (nm)	Excitation power (mW)	Spectral range (cm ⁻¹)	Resolution (cm ⁻¹)	Internal image sensor	Features
C13560	96 × 14.5 × 60	785	5, 10, 15	400 to 1850		CMOS linear image	Low power consumptionPalm sizeLow cost

Block diagram







SERS substrate J13856 (for C13560, sold separately)



Note: The J13856 is a product for customers that have purchased the C13560.

Light position, light-level, and color detection modules

Photodiode modules Photosensor amplifiers

Photodiode modules are high precision photodetectors that have built-in photodiode and a current-to-voltage converter. Because the output from these photodiode modules is an analog voltage signal, it can be easily measured with a voltmeter, etc. Photosensor amplifiers are current-to-voltage conversion amplifiers that can amplify the weak photocurrent of a photodiode with low noise levels.



Photodiode modules, Signal processing unit

(Tvp. Ta=25 °C

Type no.	Photo W × D × H (mm)	Features	Photo- diode type	Photosensitive area (mm)	Conversion impedance (V/A)	Cutoff frequency -3 dB (Hz)		Output	Power supply		
C10439-01				2.4 × 2.4	11 409	11 10					
C10439-02				5.8×5.8	H: 10 ⁹ L: 10 ⁷	H: 10 L: 1 k					
C10439-03	666		Si	10 × 10	L. 10						
C10439-07		These modules have		2.4	2.4×2.4						External newer
C10439-08	19 × 46 × 52	built-in photodiodes.Suitable for light level		5.8×5.8	11. 106	11. 4 1.	2	Analog	Extemal power supply (±5 to ±12 V)		
C10439-09		monitors, color-difference		10 × 10	H: 10 ⁶ L: 10 ⁴	H: 1 k L: 100 k* ²	_	7 tridiog			
C10439-10		meters, and flow meters	InGaAs	φ1	L. 10	L. 100 K					
C10439-11			IndaAs	ф3							
C10439-14	19 × 50 × 52		InAsSb	0.7 × 0.7	H: 10 ⁷ L: 10 ⁶	H: 100 L: 1 k					
C10475	110 × 100 × 30	 Signal processing unit for the C10439 series 	-	-	-	-	-	RS-232C	AC adapter (+12 V) or battery (one 9 V battery)		

^{*1:} Dark state *2: Output amplitude=2 Vp-p

Photosensor amplifiers

Typ. Ta=25 °C, unless otherwise noted)

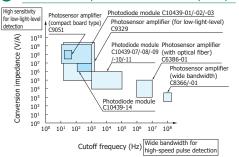
Type no.	Photo W × D × H (mm)	Features	Photodiode	Conversion impedance (V/A)	Cutoff frequency -3 dB (Hz)	Output noise voltage (mVp-p)	Output	Power supply
C6386-01		 Optical fiber included Suitable for plasma monitors and for detecting scratches and defects in metal and glass 	Built-in (optical fiber diameter ¢2 mm, NA 0.56)	H: 10 ⁵ M: 10 ⁴ L: 10 ³	H: 1 M M: 3 M L: 10 M	10 max.* ³	Analog	External power supply (±15 V) or batteries (two 9 V batteries)
C8366		• Fast and compact • Suitable for high-speed light measurement	Sold separately (high-speed Si PIN PD; photosensitive area \$0.4 to \$5 mm)	- 10 ³	100 M	3	Analog	External power
C8366-01	19 × 52 × 46	(laser power monitoring, etc.)	Sold separately (high-speed InGaAs PIN PD; photosensitive area \$0.3 to \$0.5 mm)	109	100 101	3	Analog	supply (±15 V)
C9051		 Compact board type Suitable for optical power meters and illuminometers 	Sold separately (terminal capacitance of 5 nF or less)	10 ⁸	16	0.5 max.	Analog	AC adapter (+12 V)
C9329		Ultra-low noise and high gain Suitable for low-light-level detection and precise photometry	Sold separately (terminal capacitance of 5 nF or less)	H: 10 ⁹ M: 10 ⁷ L: 10 ⁵	H: 16 M: 1.6 k L: 1.6 k	0.5 max.	Analog RS-232C	AC adapter (+12 V) or battery (one 9 V battery)

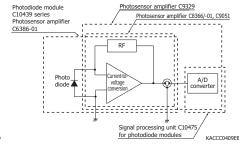
^{*3:} Dark state

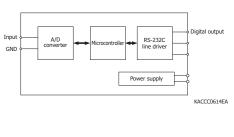
Note: Please refer to the datasheet for more information. We can also provide customized products. Please contact the sales office for more information.

Conversion impedance vs. cutoff frequency

Block diagram







[Photodiode modules, Photosensor amplifiers] [Signal processing unit for photodiode module C10475]



Connection example of photodiode modules

Photodiode module Power supply and PC Signal processing unit Photodiode AC 100 to 240 V module connection cable 50/60 Hz AC adapter*4 (for power supply)*4 C10439 series (with built-in RS-232C cable BNC-BNC cable photodiode) C10475 PC (for signal)*4 *4: Accessory for C10475 signal processing unit

Connection examples of photosensor amplifiers



^{*5:} The S8553 and S2387-1010BQ cannot be used on the C9329.

^{*6:} Can also be driven by a rectangular battery (0006P, 9 V)

^{*7:} Accessory for photosensor amplifiers

PSD modules PSD signal processing circuits

The PSD modules are position detection modules that combine a PSD (position sensitive detector) and a current-to-voltage conversion circuit in a compact case. By using a PSD module with a signal processing unit for PSD modules (sold separately), you can acquire analog and digital position signals. PSD signal processing circuits use a current-to-voltage conversion circuit to convert the photocurrent from a PSD to voltage. Some types of signal processing circuits process the resulting voltage signal and output an analog voltage, while others process the signal, convert it to digital data using an A/D converter, and then output the resulting signal.



PSD modules, Signal processing unit

(Typ. Ta=25 °C

Type no.	Photo W × D × H (mm)	Features	Photosensitive area (mm)	Position resolution (µm)	Position detection error (µm)	Cutoff frequency -3 dB (kHz)	A/D (bit)	Output	Power supply
C10443-01			4×4	0.5	±70	16			
C10443-02		Built-in two-dimensional PSD	9 × 9	1		16			External
C10443-03		• Built-III two-uimensional F3D	10 10	1.4	±150	16	-	Analog	power supply
C10443-04			12 × 12	4.2		160			(±5 to ±12 V)
C10443-06	$34 \times 40 \times 44$	Built-in quadrant photodiode	10 × 10	-	-	160			
C10460	150 × 100 × 30	• Signal processing unit for C10443-01/-02/-03/-04	-	5	*1	13.5	16	Analog RS-232C	AC Adapter (+12 V)

^{*1: ±3%}

Note: Please refer to the datasheet for more information.

PSD signal processing circuits

(Tvp. Ta=25 °C

	Photo		Compatible P							
Type no. W × D × H (mm)			Type no.		Position resolution (µm)	Conversion impedance (V/A)	Rise time (µs)	A/D (bit)	Output	Power supply
			S4581-04	2 × 1	0.8	H: 10 ⁶	22			External
C3683-02			S4583-04, S8673	3 × 1	1.3	M: 10 ⁵		-	Analog	power supply
	56 × 66 × 15.5	_	S4584 series, S3274-05	3.5×1	1.5	L: 10 ⁴				(±15 V)
	30 × 00 × 10.0	dimensional PSD	S7105 series	4.2×1	1.8	10 ⁵	*2	12	RS-232C	AC adapter (+12 V)
	75 × 110 × 15		S5629 series, S3931	6 × 1	2.5					
C9068			S3932	12 × 1	5					
			S8543	24 × 0.7	10					
			S3270	37 × 1	15.4					
C4674-01*3			S5990-01	4 × 4	1.7	H: 10 ⁶	22		Analag	External
	65 × 90 × 15.5	Two-	S5991-01	9 × 9	3.8	M: 10 ⁵ L: 10 ⁴	22	-	Analog	power supply (±15 V)
C9069*3	10.0	PSD	S2044	4.7×4.7	2	10 ⁵		12	50.000	AC adapter
	75 × 110 × 15		S1880	12 × 12	5		*2		RS-232C	(+12 V)

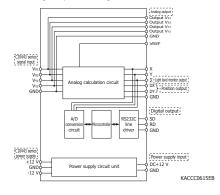
^{*2:} Signal conversion time=5 ms min.

Block diagrams

[C10443-01 to -04 PSD module] [C10460 signal processing unit for PSD module]

KACCC0345EB

Two-dimensional PSD PSD reverse bias voltage circuit Output Vx2 Output Vx2



PSD photocurrent PSD photocurrent PSD photocurrent PSD photocurrent PSD photocurrent PSD photocurrent Ava preverse bias or circuit PSD photocurrent PSD photocurrent

[C3683-02 PSD signal processing circuit]

^{*3:} Also supports quadrant photodiodes. Please contact the sales office for more information.

Note: Please refer to the datasheet for more information. We can also provide customized products. Please contact the sales office for more information.

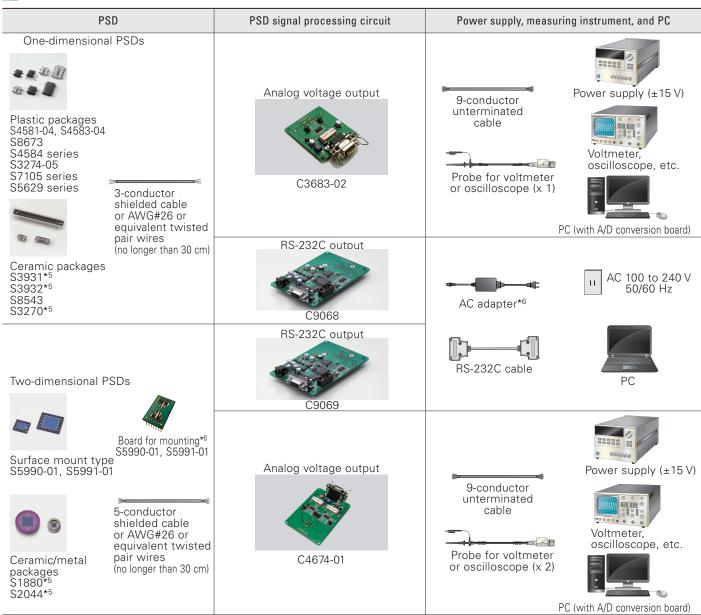


Connection example of PSD module (C10443-01/-02/-03) and signal processing unit

PSD module	Signal processing unit	Power supply, measuring instrument, and PC		
PSD module connection cable (for signal and power supply)*4 C10443-01/-02/-03/-04 (with built-in PSD)	C10460	AC adapter*4 AC 100 to 240 V 50/60 Hz Voltmeter, oscilloscope, etc. RS-232C cable PC		

^{*4:} Accessory for C10460 signal processing unit

Connection example of PSD signal processing circuits



^{*5:} Can also be directly mounted on a PSD signal processing circuit

^{*6:} Accessory for PSD signal processing circuit

Optics modules

The C13398 series is an optics module for blood analysis device featuring high blocking performance and low noise. It is composed of Si photodiodes, beam splitters, filters, and current-to-voltage conversion circuit. The C13398-01 can detect 10 wavelengths of light simultaneously. The C13398-02 can detect 9 wavelengths of light and a reference light simultaneously. In combination with the dedicated evaluation circuit C13390 (sold separately), the analog output signals of each channel of the C13398 series can be converted into digital signals, and the results can be acquired into the PC.



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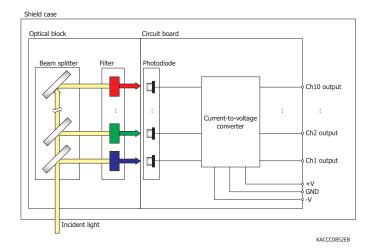
Type no.	Photo W × D × H (mm)	Detection wavelength (nm)	Conversion impedance (V/A)	Cutoff frequency -3 dB (kHz)	Output noise voltage Dark state (mVp-p)	Blocking min.
C13398-01		10 wavelengths (340, 405, 450, 510, 546, 570, 600, 630, 660, 700)	_	1.0	1	4
C13398-02	38 × 89 × 26	9 wavelengths (340, 380, 405, 492, 510, 546, 578, 620, 690) + Reference light	10 ⁷	1.6	1	4

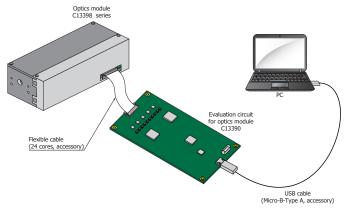
Evaluation circuit for optics module

Type no.	Photo W × D × H (mm)	Features	Full scale error max. (LSB)	Resolution max. (bit)	Output	Sample software
C13390	60 × 100 × 7.8	 USB bus powered Up to 10 channels of output signals can be acquired into a PC. 	±32	16	USB 2.0	0

Block diagram

Connection example

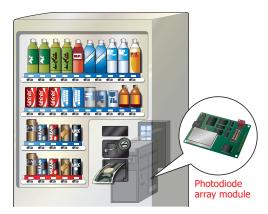




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Application examples

[Vending machine]



KACCC0605EA

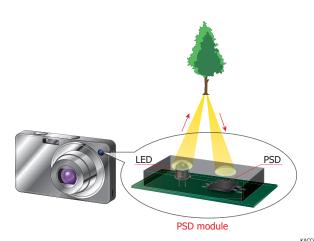
Photodiode modules can be used to detect the width and length of paper money and thereby determine its authenticity.

[IH cooking heater]



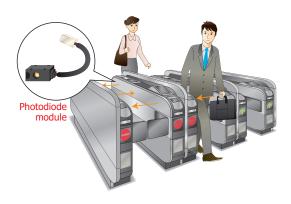
Photodiode modules can be used to detect the temperature at the bottom of a pan.

[Camera autofocusing]



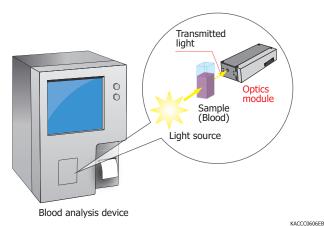
A PSD module detects how infrared light emitted onto the object is reflected, and this information is used to calculate the distance to the object.

[Automatic ticket inspection device]



Photodiode modules can be used to inspect passengers and baggage and to reduce ticket processing mistakes.

[Blood analysis device]



Optics modules can be used to analyze components contained in blood by directing light on the blood and measure the transmitted light for each wavelength.

[Solar position detection]



KACCC0608EA

Photodiode modules (or PSD modules) can be used to detect sunlight and open and close shutters or blinds.

Color sensor modules

In addition to modules with built-in color sensors, we also offer evaluation circuits that you can mount color sensors onto. These products can be used for LCD display color monitoring, simple color detection, etc.



Color sensor modules, Color sensor evaluation circuit

(Typ. Ta=25 °C

Product name		Color se	ensor module	Color sensor evaluation circuit	
Type no.	C9303-03	C9303-04	C9315	C9331	
Photo					
	Standard type	High gain type	For RGB information measurement of object color		
Features	Compact design that enables attachment to the side of the LCD backlight's light-guide plate		Has an internal white LED as the light source, converts the reflected light into RGB data, and outputs the data to a PC Measures small areas using an objective optical fiber 12-bit digital output (RS-232C compatible)	Current-to-voltage conversion amplifier allowing a Hamamatsu color sensor (S7505-01, S9032- 02) to be mounted	
Light source	N	О	Yes (white LED)	No	
Color sensor	Ye	es	Yes	No	
Conversion impedance	R: 91 kΩ G: 91 kΩ B: 100 kΩ	R: 680 kΩ G: 680 kΩ B: 680 kΩ	_	Variable (1 \times 10 ⁵ to 5.1 \times 10 ⁵ Ω)	
Cutoff frequency -3 dB	16 kHz	2.4 kHz	Digital output period: 200 ms	14 kHz	
Light source measurement	Ye	es	No	Yes	
Applications	White balance detection of LCD backlight (RGB-LED type)		Measurement of object color Color monitoring of opaque body (molded parts, painting, printing, cosmetics, etc.) Simple detection of color difference	Measurement of light source color Evaluation of S7505-01 and S9032-02	
Accessories	Dedicated cable	with connector	Dedicated AC adapter Sample software (data acquisition, recording, relative chromaticity Yxy display not conforming to CIE) White reference card	-	

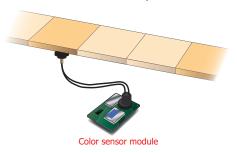
Application examples

[Color adjustment for LCD backlights]



KACCC0609EA

[Color detection of products]



KACCC0610EA

A color sensor module can be used to detect color differences in an object through the irradiation of light from the built-in LED onto the object and then the conversion of the reflected light into R, G, and B parameters.

The white balance of the LCD backlight's light-guide plate is detected, the RGB-LED light level is controlled, and the color of the LCD backlight is made to be consistent.



Balanced detectors

These are differential amplification type photoelectric conversion modules containing two Hamamatsu photodiodes with balanced characteristics. The photodiodes are connected in a direction that cancels out the photocurrent of each photodiode. This configuration cancels out the common mode noise of the two incident light rays. The minute difference in light levels is treated as a displacement signal, converted into an electrical signal, and output. Moreover, the adoption of our unique structure that suppresses multiple reflections of incident light has made it possible to reduce the noise caused by the reflections. These products can be applied to optical coherence tomography (OCT) used in ophthalmologic examinations and the like. The balanced detector can convert into electrical signals the minute difference in the signal light produced when the back scattering light from the subject is made to interfere with the reference light.



Features

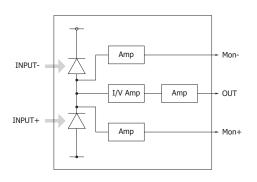
- \blacksquare Employs our unique structure that reduces multiple reflections at the incident light wavelength of 1.0 μm or 1.3 μm
- Input section: FC receptacle (APC polished)
 A single-mode fiber with an FC connector can be connected.
- Output section: SMA receptacle
- Compact

(Typ. Ta=25°C)

Type no.	Photo W × D × H (mm)		Conversion impedance (V/A)	Cutoff frequency -3 dB (MHz)	Common-mode rejection ratio*2 (dB)	Output noise voltage max. (mVp-p)	Input	Output	Supply voltage
C12668-01	G12669-01	1.0	2 104	200	25				
C12668-02	25 × 54.5 × 65	1.3	3×10^4	200	35	40	FC/APC	SMA	External power
C12668-03	CISSES OS	1.0	1 × 10 ⁴	400	30	40	FC/AFC	SIVIA	supply (±12 V)
C12668-04	25 × 78 × 72	1.3	1 × 10	400	30				

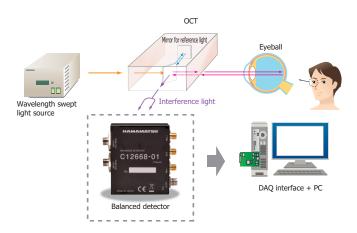
^{*1:} Wavelength band in which multiple reflections can be reduced the most

Block diagram



KACCC0761FA

Connection example (ophthalmic medical OCT)



KACCC0762EA

^{*2:} Output difference when an approximately 70 µW light is applied to only the INPUT- terminal and when applied to INPUT+ and INPUT- terminals

Flame eyes (monitors)

The "flame eye" is a sensor that monitors flames in oil boilers and heating equipment. It detects light emitted from the flame so that the combustion state can be observed. Because this flame eye has a photo IC diode instead of a conventional CdS photoconductive cell, it provides stable detection performance. The flame eye is easy to install because the sensor is integrated into the cable assembly. Two types of flame eyes with different light input directions (a head-on type and a side-on type) are available.

Features

■ Internal photo IC diode

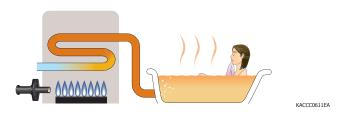
The internal photo IC diode boosts the photocurrent generated from the photodiode approx. 13000 times.

The photo IC diode outputs current and can be used the same as a photodiode applied with a reverse voltage.

- Spectral response that is suitable for detecting oil burner flames, etc.
- Cable assembly for easy installation into equipment
- Small output current variations and good output linearity



Application example (Observation of the combustion condition of a hot-water heater)



Detects light emitted from the flame so that the combustion state can be observed.

Sunlight sensor

Sunlight sensors detect the light level of sunlight and ambient light. A photodiode with superb linearity relative to the light level is built in a small case with a connector.



Features

- High reliability (for automotive use)
- The optical design of the cover makes it possible to adjust the directivity for different applications.
- Both visible light and near-infrared light sensors can be selected.

Application examples (Sunlight sensor)



A sunlight sensor can be used to detect the amount of sunshine to control the volume of air flow of an automotive air conditioner.

Related products and circuits for infrared detectors and image sensors

Infrared detector modules with preamp

These modules integrate preamps and various infrared detectors. Modules are available for a variety of different wavelength ranges. You can detect infrared light simply by connecting a DC power supply.

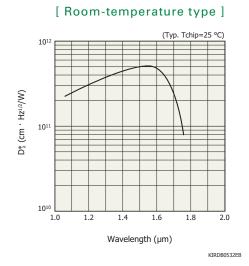


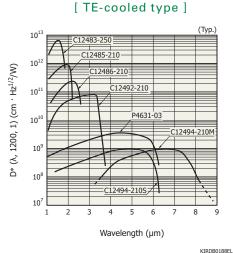
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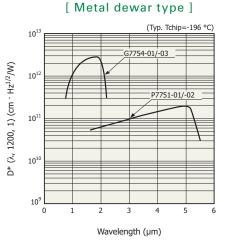
Туре	Type no.	Photo	Detector (built-in)	Photosensitive area (mm)	Cooling	Measurement condition Chip temperature (°C)	Cutoff wavelength (µm)	Peak sensitivity wavelength (µm)
Room-	G6121		InGaAs (G8370-05)	ф5	No cooling	0.5	1.7	1.55
temperature type	C12496-046		Photon drag (B749)	ф4.6		25	-	10.6
	C12483-250		InGaAs (G12180-250A)	ф5			1.66	1.55
TE-cooled type	C12485-210		InGaAs (G12182-210K)	- ф1	TE-cooling	-15	2.05	1.95
	C12486-210		InGaAs (G12183-210K)				2.56	2.3
	C12492-210		InAs (P10090-21)	ф1		-28	3.45	3.25
τγρο	P4631-03		InSb (P6606-310)	1 × 1		-58	6.1	5.5
	C12492-210S		InAsSb (P11120-201)	1		00	5.9	4.9
	C12492-210M	6 °	InAsSb (P12691-201)	ф1		-28	8.3	6.7
	G7754-01		InGaAs (G12183-010)*1	φ1			2.4	2.0
Metal dewar	G7754-03		InGaAs (G12183-030)*1	ф3	Liquid nitrogen	-196	2.4	2.0
type	P7751-01* ²		InSb (P5968-060)	ф0.6			5.5	5.3
	P7751-02*2		InSb (P5968-200)	ф2			5.5	0.0

^{*1:} Chip *2: FOV=60°

Spectral response







KIRDB0612EA

Multichannel detector heads

Because the electronics and signal processing of image sensors are more complicated than those of single-element sensors, we offer multichannel detector heads that can be connected to sensors and used. It's easy to use these detector heads with a controller and software to gather data.



Туре	Type no.	Output	Applicable sensors	Applicable sensors		
	C7020		S9970 series			
	C7020-02		S9972 series			
For front-illuminated	C7021	Analas	S9971-0906/-1006/-1007	Sold		
CCD image sensor	C7021-02	Analog	S9973-1007	separately		
	C7025		S9971-1008			
	C7025-02		S9973-1008			
	C7040		S7030 series			
	C7041		S7031 series			
For back-thinned	C7043		S7033 series	Sold		
CCD image sensor	C7044	Analog	S7034 series	separately		
	C7180		S7170-0909			
	C7181		S7171-0909-01			
For NMOS	C5964 series		S5930/S5931/S8382/S8383 series	Built-in		
linear image sensor	C8892	Analog	S3901 to S3904/S8380/S8381 series (excluding S3901-1024Q and S3904-2048Q)	Sold separately		
	C10854	CameraLink	G10768 series			
For InGaAs linear image sensor	C8061-01		G9201/G9203/G9211/G9213-256S G9202/G9204/G9212/G9214-512S	Sold separately		
illiedi illiage selisti	C8062-01	Analog	G9205/G9206/G9207/G9208-256W G9205/G9206/G9208-512W G9206-02	Sopulatory		
For InGaAs	C11512	CameraLink	G11097-0606S, G12460-0606S	Sold		
area image sensor	C11512-02	CameraLink	G12242-0707W	separately		

Related products



Controller for multichannel detector head C7557-01

(Applicable with analog output type CCD/NMOS/InGaAs multichannel detector heads)



Circuits for image sensors

These are driver circuits for CCD, NMOS, and CMOS image sensors.



Type	Type no.	Output	Features	Applicable sensor	rs
	C11287		Signal frequency: 250 kHz, USB 2.0, USB bus power	S10420-01 series	
	C11288		Signal frequency: 4 MHz, USB 2.0	S11071 series	
Driver circuit for CCD image sensor	C11165-01	Digital	Signal frequency: 6 MHz, USB 2.0	S11155/S11156-2048-01	
	C11165-02		Signal frequency: 6 MHz, USB 2.0	S11155/S11156-2048-02	Sold separately
	C11860		Single power supply, USB 2.0	S11850-1106	
Driver circuit for	C7884	Analaa	High-precision, current output type	S3901 to S3904 series S8380/S8381 series	
NMOS image sensor	C7884-01	Analog	Low noise, current output type	(excluding S3901-1024Q and S3904-2048Q)	
	C9001		Single power supply (+5 V) operation	S8377/S8378 series	
Driver circuit for CMOS image sensor	C10808 series	Analog	Supports variable integration time	S10111 to S10114/S10121 to S10124 series	1
	C13015-01	Digital	USB 2.0, USB bus power	S11639-01, S11638, S12706, S13496	
	C10820	Analog	High-gain settings for low light levels	G9494 series	
Driver circuit for InGaAs image sensor	C11513	- Digital	USB 2.0, USB bus power	G11620 series (except cooled type)	
	C11514	Digital	CameraLink compatible	G11135 series, G14006-512DE	



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Main Products

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